

# MC1558 MC1458 MC1458C

## OPERATIONAL AMPLIFIERS

### DUAL MC1741 INTERNALLY COMPENSATED, HIGH PERFORMANCE MONOLITHIC OPERATIONAL AMPLIFIER

... designed for use as a summing amplifier, integrator, or amplifier with operating characteristics as a function of the external feedback components.

- No Frequency Compensation Required
- Short-Circuit Protection
- Wide Common-Mode and Differential Voltage Ranges
- Low-Power Consumption
- No Latch Up

### (DUAL MC1741) DUAL OPERATIONAL AMPLIFIER

MONOLITHIC SILICON  
INTEGRATED CIRCUIT

G SUFFIX  
METAL PACKAGE  
CASE 601  
TO-99



L SUFFIX  
CERAMIC PACKAGE  
CASE 632  
TO-116

P1 SUFFIX  
PLASTIC PACKAGE  
CASE 626  
MC1458,C (only)



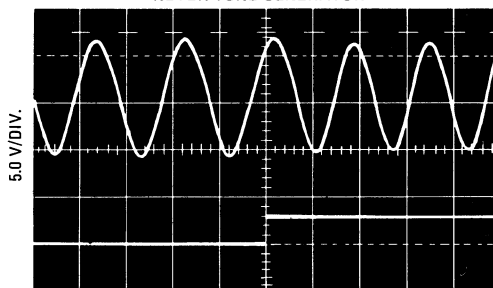
P2 SUFFIX  
PLASTIC PACKAGE  
CASE 605  
MC1458,C (only)



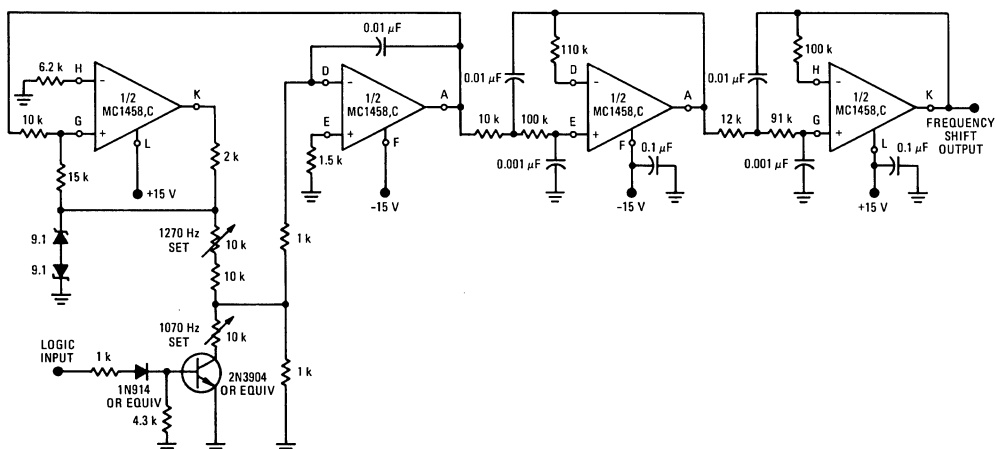
#### PIN CONNECTIONS

Schematic	A	B	C	D	E	F	G	H	I	J	K	L
G & P1 Packages	1	-	-	2	3	4	5	6	-	-	7	8
L & P2 Packages	2	3	4	5	6	7	8	9	10	11	12	14

FIGURE 1 - TYPICAL FREQUENCY-SHIFT  
KEYER TONE GENERATOR



0.5 ms/DIV.



MC1558, MC1458, MC1458C(continued)

MAXIMUM RATINGS (T<sub>A</sub> = +25°C unless otherwise noted)

Rating	Symbol	MC1558	MC1458,C	Unit
Power Supply Voltage	V <sup>+</sup> - V <sup>-</sup>	+22 -22	+18 -18	Vdc
Differential Input Signal ①	V <sub>in</sub>	±30		Volts
Common-Mode Input Swing ②	CMV <sub>in</sub>	±15		Volts
Output Short Circuit Duration	I <sub>S</sub>	Continuous		
Power Dissipation (Package Limitation)	P <sub>D</sub>			
Metal Can		680		mW
Derate above T <sub>A</sub> = +25°C		4.6		mW/°C
Plastic Dual In-Line Packages		625		mW
Derate above T <sub>A</sub> = +25°C		5.0		mW/°C
Ceramic Dual In-Line Package		750		mW/°C
Derate above T <sub>A</sub> = +25°C		6.0		mW/°C
Operating Temperature Range	T <sub>A</sub>	-55 to +125	0 to +75	°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	-65 to +150	°C

ELECTRICAL CHARACTERISTICS (V<sup>+</sup> = +15 Vdc, V<sup>-</sup> = -15 Vdc, T<sub>A</sub> = +25°C unless otherwise noted)

Characteristics	Symbol	MC1558			MC1458			MC1458C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Bias Current T <sub>A</sub> = +25°C T <sub>A</sub> = T <sub>low</sub> to T <sub>high</sub> ③	I <sub>b</sub>	-	0.2	0.5	-	0.2	0.5	-	0.2	0.7	μAdc
Input Offset Current T <sub>A</sub> = +25°C T <sub>A</sub> = T <sub>low</sub> to T <sub>high</sub>	I <sub>io</sub>	-	0.03	0.2	-	0.03	0.2	-	0.03	0.3	μAdc
Input Offset Voltage (R <sub>S</sub> ≤ 10 k Ω) T <sub>A</sub> = +25°C T <sub>A</sub> = T <sub>low</sub> to T <sub>high</sub>	V <sub>io</sub>	-	1.0	5.0	-	2.0	6.0	-	2.0	10	mVdc
Differential Input Impedance (Open-Loop, f = 20 Hz)											
Parallel Input Resistance	R <sub>p</sub>	0.3	1.0	-	0.3	1.0	-	-	1.0	-	Megohm
Parallel Input Capacitance	C <sub>p</sub>	-	6.0	-	-	6.0	-	-	6.0	-	pF
Common-Mode Input Impedance (f = 20 Hz)	Z <sub>(in)</sub>	-	200	-	-	200	-	-	200	-	Megohms
Common-Mode Input Voltage Swing	CMV <sub>in</sub>	±12	±13	-	±12	±13	-	±11	±13	-	Vpk
Equivalent Input Noise Voltage (A <sub>v</sub> = 100, R <sub>s</sub> = 10 k ohms, f = 1.0 kHz, BW = 1.0 Hz)	e <sub>n</sub>	-	45	-	-	45	-	-	45	-	nV/(Hz) <sup>1/2</sup>
Common-Mode Rejection Ratio (f = 100 Hz)	CM <sub>rej</sub>	70	90	-	70	90	-	60	90	-	dB
Open-Loop Voltage Gain T <sub>A</sub> = +25°C T <sub>A</sub> = T <sub>low</sub> to T <sub>high</sub> } (V <sub>O</sub> = ±10 V, R <sub>L</sub> = 2.0 k ohms) T <sub>A</sub> = +25°C T <sub>A</sub> = T <sub>low</sub> to T <sub>high</sub> } (V <sub>O</sub> = ±10 V, R <sub>L</sub> = 10 k ohms)	A <sub>VOL</sub>	50,000 25,000	200,000 -	- 15,000	20,000 100,000	- -	- -	- 20,000	- 100,000	- 15,000	V/V
Power Bandwidth (A <sub>v</sub> = 1, R <sub>L</sub> = 2.0 k ohms, THD ≤ 5%, V <sub>O</sub> = 20 V p-p)	P <sub>BW</sub>	-	14	-	-	14	-	-	14	-	kHz
Unity Gain Crossover Frequency (open-loop)	f <sub>c</sub>	-	1.1	-	-	1.1	-	-	1.1	-	MHz
Phase Margin (open-loop, unity gain)		-	65	-	-	65	-	-	65	-	degrees
Gain Margin		-	11	-	-	11	-	-	11	-	dB
Slew Rate (Unity Gain)	dV <sub>out</sub> /dt	-	0.8	-	-	0.8	-	-	0.8	-	V/μs
Output Impedance (f = 20 Hz)	Z <sub>out</sub>	-	75	-	-	75	-	-	75	-	ohms
Short-Circuit Output Current	I <sub>SC</sub>	-	20	-	-	20	-	-	20	-	mAdc
Output Voltage Swing (R <sub>L</sub> = 10 k ohms) R <sub>L</sub> = 2 k ohms (T <sub>A</sub> = T <sub>low</sub> to T <sub>high</sub> )	V <sub>O</sub>	±12 ±10	±14 ±13	- ±10	±12 ±10	±14 ±13	- ±9.0	±11 ±13	±14 ±13	-	Vpk
Average Temperature Coefficient of Input Offset Voltage (R <sub>S</sub> = 50 ohms, T <sub>A</sub> = T <sub>low</sub> to T <sub>high</sub> )	TCV <sub>io</sub>	-	15	-	-	15	-	-	15	-	μV/°C
Power Supply Sensitivity V <sup>-</sup> = constant, R <sub>s</sub> ≤ 10 k ohms V <sup>+</sup> = constant, R <sub>s</sub> ≤ 10 k ohms	S <sup>+</sup> S <sup>-</sup>	-	30	150	-	30	150	-	30	-	μV/V
Power Supply Current	I <sub>D</sub> <sup>+</sup> I <sub>D</sub> <sup>-</sup>	-	2.3	5.0	-	2.3	5.6	-	2.3	8.0	mAdc
DC Quiescent Power Dissipation (V <sub>O</sub> = 0)	P <sub>D</sub>	-	70	150	-	70	170	-	70	240	mW

① For supply voltages of less than ±15 V, the maximum differential input voltage is equal to ±(V<sup>+</sup> + |V<sup>-</sup>|).

② For supply voltages of less than ±15 V, the maximum input voltage is equal to the supply voltage (+V<sup>+</sup>, -|V<sup>-</sup>|).

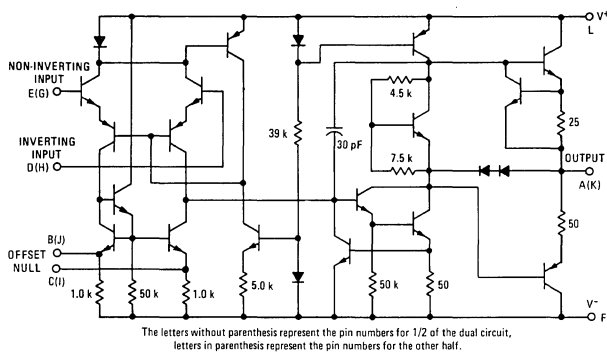
③ T<sub>low</sub>: 0°C for MC1458,C

-55°C for MC1558

T<sub>high</sub>: +75°C for MC1458,C

+125°C for MC1558

FIGURE 2 – CIRCUIT SCHEMATIC

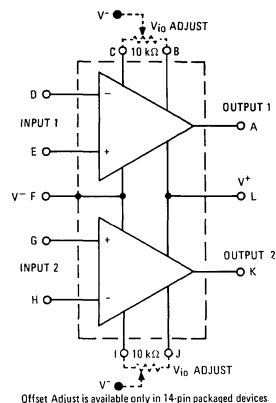


The letters without parenthesis represent the pin numbers for 1/2 of the dual circuit, letters in parenthesis represent the pin numbers for the other half.

PIN CONNECTIONS

Schematic	A	B	C	D	E	F	G	H	I	J	K	L
G & P1 Packages	1	—	—	2	3	4	5	6	—	—	7	8
L & P2 Packages	2	3	4	5	6	7	8	9	10	11	12	14

FIGURE 3 – EQUIVALENT CIRCUIT WITH OFFSET ADJUST



Offset Adjust is available only in 14-pin packaged devices.

TYPICAL CHARACTERISTICS

( $V^+ = +15$  Vdc,  $V^- = -15$  Vdc,  $T_A = +25^\circ\text{C}$  unless otherwise noted.)

FIGURE 4 – OPEN-LOOP VOLTAGE GAIN  
versus POWER-SUPPLY VOLTAGE

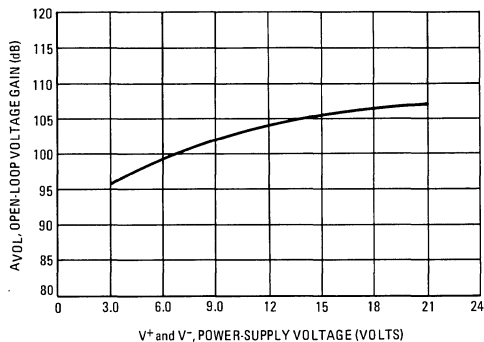


FIGURE 5 – OPEN-LOOP FREQUENCY RESPONSE

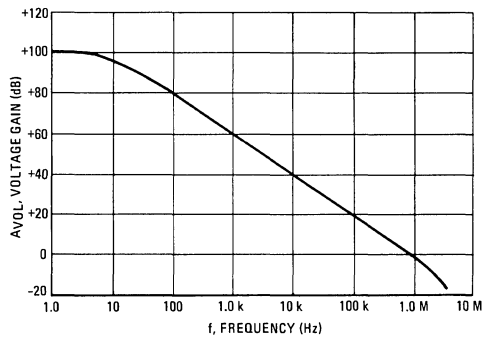


FIGURE 6 – POWER BANDWIDTH  
(LARGE SIGNAL SWING versus FREQUENCY)

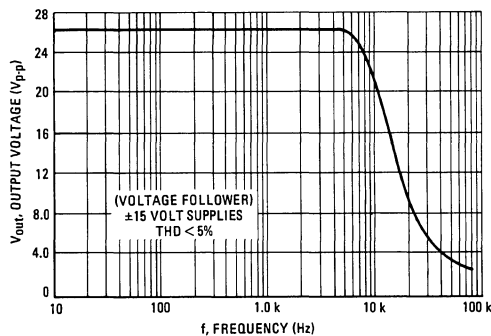
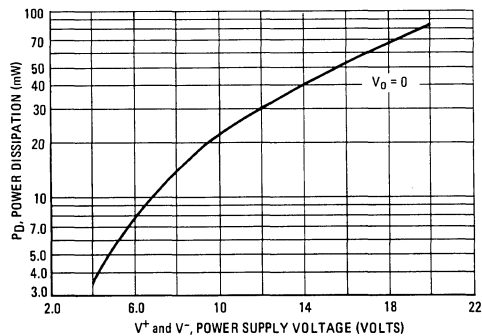


FIGURE 7 – POWER DISSIPATION  
versus POWER SUPPLY VOLTAGE



TYPICAL CHARACTERISTICS (continued)

( $V^+ = +15$  Vdc,  $V^- = -15$  Vdc,  $T_A = +25^\circ\text{C}$  unless otherwise noted.)

FIGURE 8 – OUTPUT VOLTAGE SWING  
versus LOAD RESISTANCE

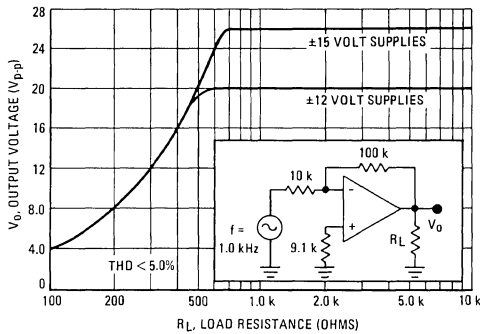


FIGURE 9 – OUTPUT NOISE versus SOURCE RESISTANCE

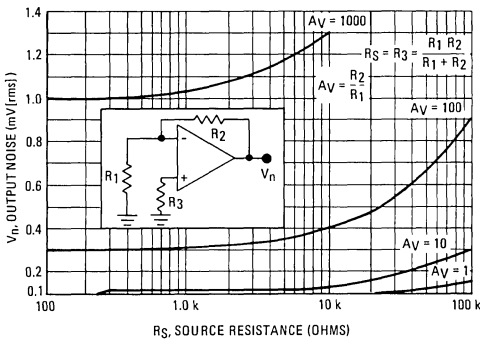
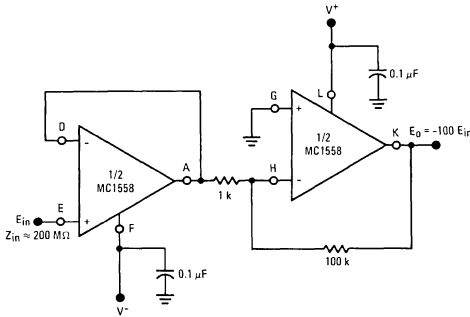


FIGURE 10 – HIGH-IMPEDANCE, HIGH-GAIN  
INVERTING AMPLIFIER



## MCC1558 MCC1458

### Advance Information

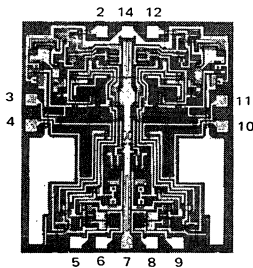
#### DUAL MC1741 INTERNALLY COMPENSATED, HIGH PERFORMANCE MONOLITHIC OPERATIONAL AMPLIFIER CHIP

... designed for use as a summing amplifier, integrator, or amplifier with operating characteristics as a function of the external feedback components.

The MCC1558 and MCC1458 employ phosphorsilicate passivation that protects the entire die surface area, including metalization interconnects. All dice have a minimum gold-backed thickness of 4000 Angstroms. The interconnecting metalization and bonding pads are of evaporated aluminum.

- No Frequency Compensation Required
- Short-Circuit Protection
- Wide Common-Mode and Differential Voltage Ranges
- Low-Power Consumption
- No Latch Up

#### (DUAL MC1741) DUAL OPERATIONAL AMPLIFIER CHIP INTEGRATED CIRCUIT MONOLITHIC SILICON



#### MAXIMUM RATINGS ( $T_A = +25^{\circ}\text{C}$ unless otherwise noted)

Rating	Symbol	MCC1558	MCC1458	Unit
Power Supply Voltage	$V^+$ $V^-$	+22 -22	+18 -18	Vdc
Differential Input Signal	$V_{in}$	$\pm 30$		Volts
Common-Mode Input Swing	$CMV_{in}$	$\pm 15$		Volts
Output Short Circuit Duration	$t_S$	Continuous		
Operating Temperature Range	$T_A$	-55 to +125		$^{\circ}\text{C}$
Junction Temperature Range	$T_J$	-65 to +150		$^{\circ}\text{C}$

FIGURE 1 – CIRCUIT SCHEMATIC

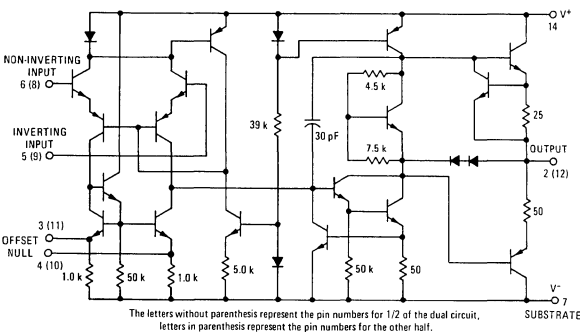
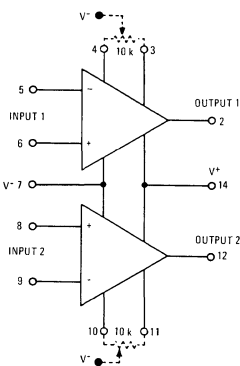


FIGURE 2 – OFFSET ADJUST



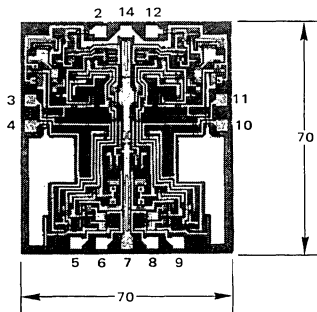
MCC1558, MCC1458 (continued)

ELECTRICAL CHARACTERISTICS ( $V^+ = +15\text{ Vdc}$ ,  $V^- = -15\text{ Vdc}$ ,  $T_A = +25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	MCC1558			MCC1458			Unit
		Min	Typ	Max	Min	Typ	Max	
Input Bias Current	$I_b$	—	0.2	0.5	—	0.2	0.5	$\mu\text{Adc}$
Input Offset Current	$ I_{io} $	—	0.03	0.2	—	0.03	0.2	$\mu\text{Adc}$
Input Offset Voltage ( $R_S \leq 10\text{ k ohms}$ )	$ V_{io} $	—	1.0	5.0	—	2.0	6.0	mVdc
Differential Input Impedance (Open-Loop, $f = 20\text{ Hz}$ )	$R_D$	—	1.0	—	—	1.0	—	Megohm
Parallel Input Resistance	$C_D$	—	6.0	—	—	6.0	—	pF
Parallel Input Capacitance								
Common-Mode Input Impedance ( $f = 20\text{ Hz}$ )	$Z_{(in)}$	—	200	—	—	200	—	Megohms
Common-Mode Input Voltage Swing	$CMV_{in}$	—	$\pm 13$	—	—	$\pm 13$	—	Vpk
Common-Mode Rejection Ratio ( $f = 100\text{ Hz}$ )	$CM_{rej}$	—	90	—	—	90	—	dB
Open-Loop Voltage Gain ( $V_O = \pm 10\text{ V}$ , $R_L = 2.0\text{ k ohms}$ )	$A_{VOL}$	50,000	200,000	—	20,000	100,000	—	V/V
Power Bandwidth ( $A_V = 1$ , $R_L = 2.0\text{ k ohms}$ , $THD \leq 5\%$ , $V_O = 20\text{ V}_{p-p}$ )	$P_{BW}$	—	14	—	—	14	—	kHz
Unity Gain Crossover Frequency (open-loop)		—	1.1	—	—	1.1	—	MHz
Phase Margin (open-loop, unity gain)		—	65	—	—	65	—	degrees
Gain Margin		—	11	—	—	11	—	dB
Slew Rate (Unity Gain)	$dV_{out}/dt$	—	0.8	—	—	0.8	—	V/ $\mu\text{s}$
Output Impedance ( $f = 20\text{ Hz}$ )	$Z_{out}$	—	75	—	—	75	—	ohms
Short-Circuit Output Current	$I_{SC}$	—	20	—	—	20	—	mAdc
Output Voltage Swing ( $R_L = 10\text{ k ohms}$ )	$V_O$	$\pm 12$	$\pm 14$	—	$\pm 12$	$\pm 14$	—	Vpk
Power Supply Sensitivity $V^- = \text{constant}$ , $R_S \leq 10\text{ k ohms}$	$S^+$	—	30	150	—	30	150	$\mu\text{V/V}$
$V^+ = \text{constant}$ , $R_S \leq 10\text{ k ohms}$	$S^-$	—	30	150	—	30	150	$\mu\text{V/V}$
Power Supply Current	$I_{D^+}$	—	2.3	5.0	—	2.3	5.6	mAdc
	$I_{D^-}$	—	2.3	5.0	—	2.3	5.6	mAdc
DC Quiescent Power Dissipation ( $V_O = 0$ )	$P_D$	—	70	150	—	70	170	mW

See current MC1558/MC1458 data sheet for additional information.

MCC1558/MCC1458 BONDING DIAGRAM



All dimensions are nominal and in mils ( $10^{-3}$  inches).  
Die Dimensions  
Thickness = 8.0  
Bonding Pads = 4.0 x 4.0

PACKAGING AND HANDLING

The MCC1558/MCC1458 dual operational amplifiers are now available as a single monolithic die or encapsulated in a variety of hermetic and plastic packages. The phosphorsilicate passivation protects the metalization and active area of the die but care must be exercised when removing the dice from the shipping carrier to avoid scratching the bonding pads. A vacuum pickup is useful for the handling of dice. Tweezers are not recommended for this purpose.

The non-spill type shipping carrier consists of a compartmentalized tray and fitted cover. Die are placed in the carrier with geometry side up.